Preferred Device

Silicon Hot-Carrier Diodes

SCHOTTKY Barrier Diodes

These devices are designed primarily for high–efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low–cost, high–volume consumer and industrial/commercial requirements. They are also available in a Surface Mount package.

Features

- Extremely Low Minority Carrier Lifetime 15 ps (Typ)
- Very Low Capacitance -1.5 pF (Max) @ V_R = 15 V
- Low Reverse Leakage $I_R = 13$ nAdc (Typ) MBD301, MMBD301
- Pb–Free Packages are Available

MAXIMUM RATINGS

		MBD301	MMBD301LT1	
Rating	Symbol	Value		Unit
Reverse Voltage	V _R	30		V
Total Device Dissipation @ $T_A = 25^{\circ}C$ Derate above 25°C	P _F	280 2.8	200 2.0	mW mW/°C
Operating and Storage Junction Temperature Range	ТJ	-55 to +125		°C
Storage Temperature Range	T _{stg}	-55 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



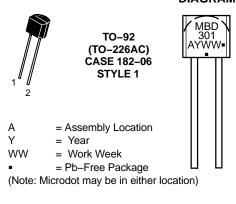
ON Semiconductor®

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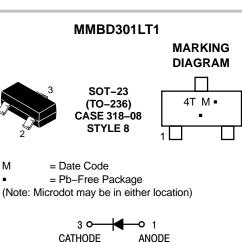
30 VOLTS SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES

MBD301

MARKING DIAGRAM



2 O 1 CATHODE ANODE



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

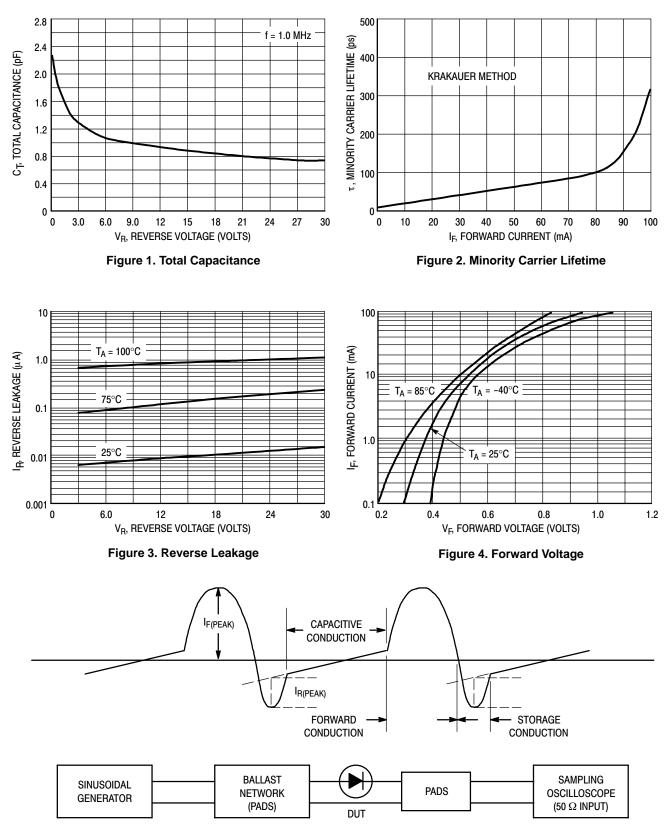
Characteristic		Min	Тур	Мах	Unit
Reverse Breakdown Voltage (I _R = 10 μ A)	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 15 V, f = 1.0 MHz) Figure 1	CT	-	0.9	1.5	pF
Reverse Leakage ($V_R = 25 V$) Figure 3	I _R	-	13	200	nAdc
Forward Voltage (I _F = 1.0 mAdc) Figure 4	V _F	-	0.38	0.45	Vdc
Forward Voltage (I _F = 10 mAdc) Figure 4	V _F	-	0.52	0.6	Vdc

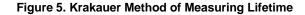
ORDERING INFORMATION

Device	Package	Shipping [†]		
MBD301	TO-92	5,000 Units / Bulk		
MBD301G	TO-92 (Pb-Free)	5,000 Units / Bulk		
MMBD301LT1	SOT-23	3,000 / Tape & Reel		
MMBD301LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel		
MMBD301LT3	SOT-23	10,000 / Tape & Reel		
MMBD301LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

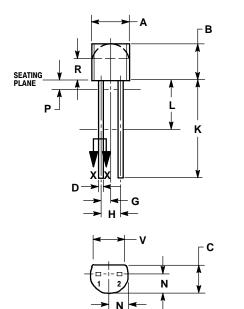






PACKAGE DIMENSIONS

TO-92 (TO-226AC) CASE 182-06 ISSUE L







NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND ZONE R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

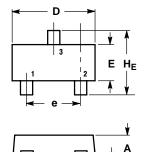
	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.175	0.205	4.45	5.21	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016 0.021		0.407	0.533	
G	0.050 BSC		1.27 BSC		
н	0.100 BSC		2.54 BSC		
J	0.014	0.016	0.36	0.41	
K	0.500		12.70		
L	0.250		6.35		
N	0.080	0.105	2.03	2.66	
P		0.050		1.27	
R	0.115		2.93		
۷	0.135		3.43		

STYLE 1: PIN 1. ANODE 2. CATHODE

http://onsemi.com

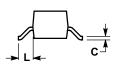
PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AL**



Å

A1



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BACE MATERIAL
- BASE MATERIAL. 318–01 THRU –07 AND –09 OBSOLETE, NEW STANDARD 318–08. 4.

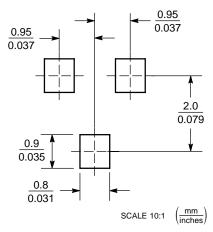
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
с	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104



b

- ANODE NO CONNECTION
- 3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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